

74F10

Triple 3-Input NAND Gate

This device contains three independent gates, each of which performs the logic NAND function.

Rochester Electronics Manufactured Components

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Parts are tested using original factory test programs or Rochester developed test solutions to guarantee product meets or exceeds the OCM data sheet.

Quality Overview

- ISO-9001
- AS9120 certification
- Qualified Manufacturers List (QML) MIL-PRF-35835
 - Class Q Military
 - Class V Space Level
- Qualified Suppliers List of Distributors (QSLD)
 - Rochester is a critical supplier to DLA and meets all industry and DLA standards.

Rochester Electronics, LLC is committed to supplying products that satisfy customer expectations for quality and are equal to those originally supplied by industry manufacturers.

The original manufacturer's datasheet accompanying this document reflects the performance and specifications of the Rochester manufactured version of this device. Rochester Electronics guarantees the performance of its semiconductor products to the original OCM specifications. 'Typical' values are for reference purposes only. Certain minimum or maximum ratings may be based on product characterization, design, simulation, or sample testing.

FOR REFERENCE ONLY

74F10

Triple 3-Input NAND Gate

General Description

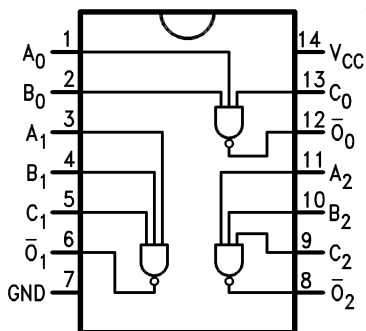
This device contains three independent gates, each of which performs the logic NAND function.

Ordering Information

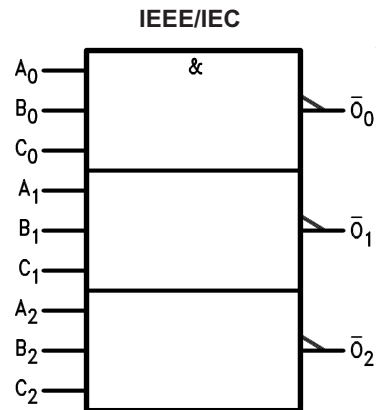
Order Number	Package Number	Package Description
74F10SC	M14A	14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow
74F10SJ	M14D	14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering number.

Connection Diagram



Logic Symbol



Unit Loading/Fan Out

Pin Names	Description	U.L. HIGH/LOW	Input I_{IH}/I_{IL} , Output I_{OH}/I_{OL}
A_n, B_n, C_n	Inputs	1.0 / 1.0	20 μ A / -0.6mA
\bar{O}_n	Outputs	50 / 33.3	-1mA / 20mA

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Rating
T_{STG}	Storage Temperature	-65°C to $+150^{\circ}\text{C}$
T_A	Ambient Temperature Under Bias	-55°C to $+125^{\circ}\text{C}$
T_J	Junction Temperature Under Bias	-55°C to $+150^{\circ}\text{C}$
V_{CC}	V_{CC} Pin Potential to Ground Pin	-0.5V to $+7.0\text{V}$
V_{IN}	Input Voltage ⁽¹⁾	-0.5V to $+7.0\text{V}$
I_{IN}	Input Current ⁽¹⁾	-30mA to $+5.0\text{mA}$
V_O	Voltage Applied to Output in HIGH State (with $V_{CC} = 0\text{V}$)	
	Standard Output	-0.5V to V_{CC}
	3-STATE Output	-0.5V to 5.5V
	Current Applied to Output in LOW State (Max.)	twice the rated I_{OL} (mA)

Note:

1. Either voltage limit or current limit is sufficient to protect inputs.

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Rating
T_A	Free Air Ambient Temperature	0°C to $+70^{\circ}\text{C}$
V_{CC}	Supply Voltage	$+4.5\text{V}$ to $+5.5\text{V}$

DC Electrical Characteristics

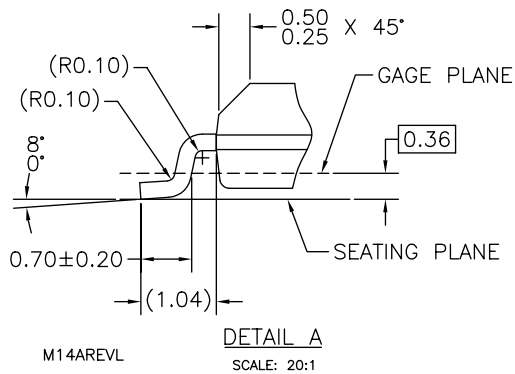
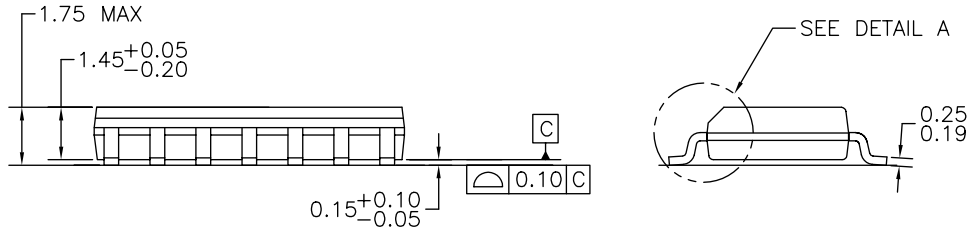
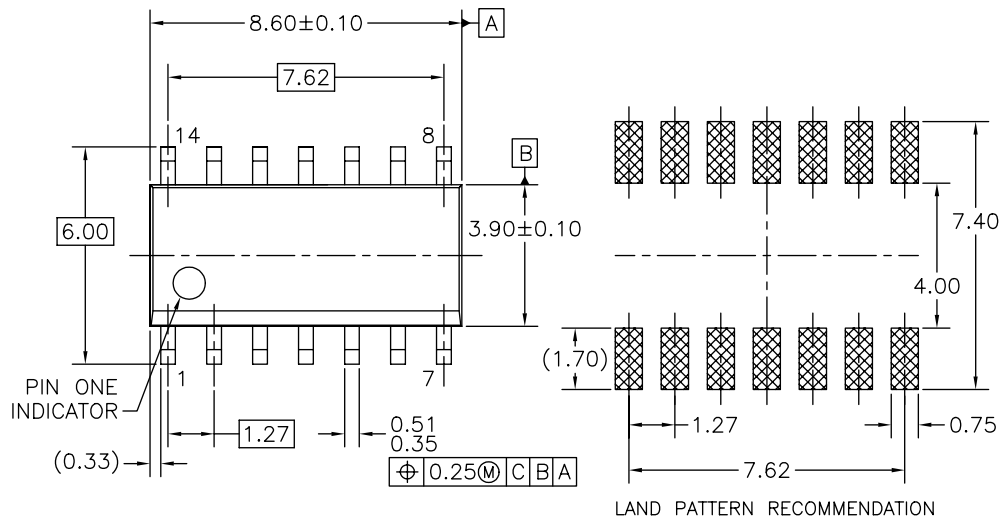
Symbol	Parameter		V _{CC}	Conditions	Min.	Typ.	Max.	Units
V _{IH}	Input HIGH Voltage			Recognized as a HIGH Signal	2.0			V
V _{IL}	Input LOW Voltage			Recognized as a LOW Signal			0.8	V
V _{CD}	Input Clamp Diode Voltage		Min.	I _{IN} = -18mA			-1.2	V
V _{OH}	Output HIGH Voltage	10% V _{CC}	Min.	I _{OH} = -1mA	2.5			V
		5% V _{CC}		I _{OH} = -1mA	2.7			
V _{OL}	Output LOW Voltage	10% V _{CC}	Min.	I _{OL} = 20mA			0.5	V
I _{IH}	Input HIGH Current		Max.	V _{IN} = 2.7V			5.0	μA
I _{BVI}	Input HIGH Current Breakdown Test		Max.	V _{IN} = 7.0V			7.0	μA
I _{CEx}	Output HIGH Leakage Current		Max.	V _{OUT} = V _{CC}			50	μA
V _{ID}	Input Leakage Test		0.0	I _{ID} = 1.9μA, All other pins grounded	4.75			V
I _{OD}	Output Leakage Circuit Current		0.0	V _{IOD} = 150mV, All other pins grounded			3.75	μA
I _{IL}	Input LOW Current		Max.	V _{IN} = 0.5V			-0.6	mA
I _{OS}	Output Short-Circuit Current		Max.	V _{OUT} = 0V	-60		-150	mA
I _{CCH}	Power Supply Current		Max.	V _O = HIGH		1.4	2.1	mA
I _{CCL}	Power Supply Current		Max.	V _O = LOW		5.1	7.7	mA

AC Electrical Characteristics

Symbol	Parameter	T _A = +25°C, V _{CC} = +5.0V, C _L = 50pF			T _A = -55°C to +125°C, V _{CC} = +5.0V, C _L = 50 pF		T _A = 0°C to +70°C, V _{CC} = +5.0V, C _L = 50pF		Units
		Min.	Typ.	Max.	Min.	Max.	Min.	Max.	
t _{PLH}	Propagation Delay, A _n , B _n , C _n to \overline{O}_n	2.4	3.7	5.0	2.0	7.0	2.4	6.0	ns
t _{PHL}		1.5	3.2	4.3	1.5	6.5	1.5	5.3	

Physical Dimensions

Dimensions are in millimeters unless otherwise noted.



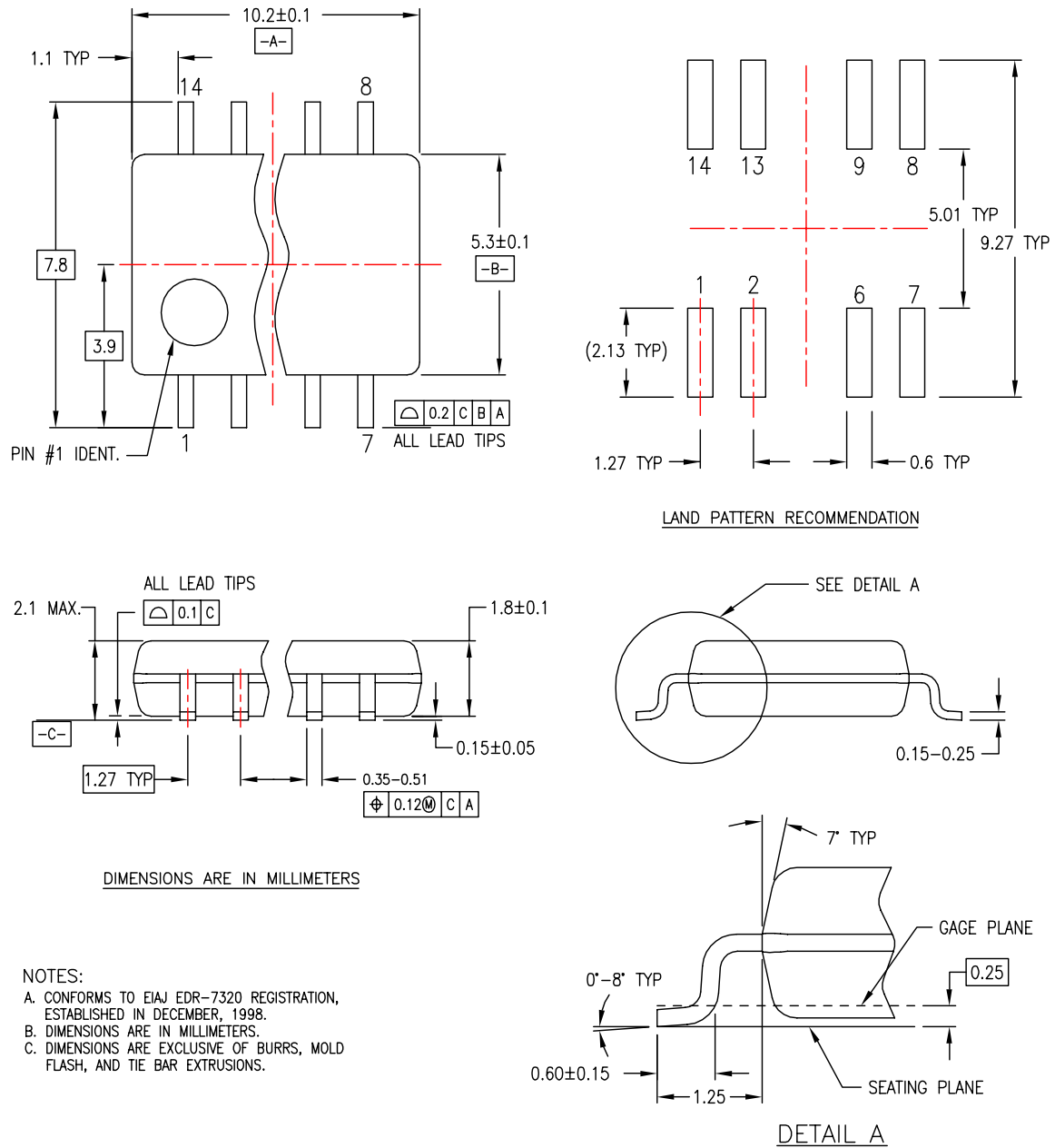
NOTES: UNLESS OTHERWISE SPECIFIED

- A) THIS PACKAGE CONFORMS TO JEDEC MS-012, VARIATION AB, ISSUE C, DATED MAY 1990.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS.

Figure 1. 14-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150" Narrow Package Number M14A

Physical Dimensions (Continued)

Dimensions are in millimeters unless otherwise noted.



NOTES:

- A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.


M14DREVC

Figure 2. 14-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide Package Number M14D



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Preliminary	First Production	This datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild Semiconductor. The datasheet is printed for reference information only.

Rev. 126